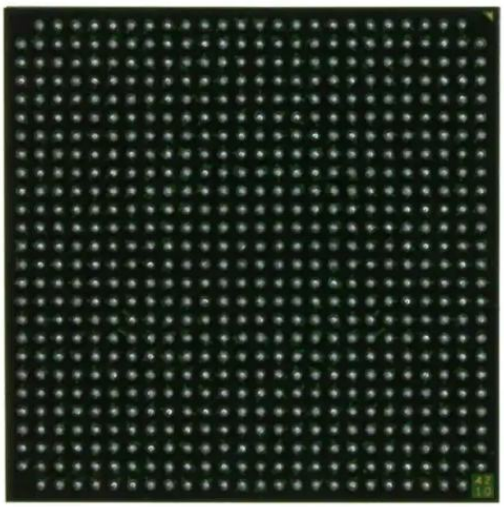

Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	1232
Number of Logic Elements/Cells	11088
Total RAM Bits	811008
Number of I/O	396
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FCBGA (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp7-6ffg672c

Revision History

This section records the change history for this module of the data sheet.

Date	Version	Revision
01/31/02	1.0	Initial Xilinx release.
06/13/02	2.0	New Virtex-II Pro family members. New timing parameters per speedsfile **v1.62**.
09/03/02	2.1	Updates to Table 1 and Table 3. Processor Block information added to Table 4.
09/27/02	2.2	In Table 1, correct max number of XC2VP30 I/Os to 644.
11/20/02	2.3	Add bullet items for 3.3V I/O features.
01/20/03	2.4	• In Table 3, add FG676 package option for XC2VP20, XC2VP30, and XC2VP40. • Remove FF1517 package option for XC2VP40.
03/24/03	2.4.1	• Correct number of single-ended I/O standards from 19 to 22. • Correct minimum RocketIO serial speed from 622 Mbps to 600 Mbps.
08/25/03	2.4.2	• Add footnote referring to XAPP659 to callout for 3.3V I/O standards on page 4.
12/10/03	3.0	• XC2VP2 through XC2VP70 speed grades -5, -6, and -7, and XC2VP100 speed grades -5 and -6, are released to **Production status**.
02/19/04	3.1	• Table 1: Corrected number of RocketIO transceiver blocks for XC2VP40. • Section Virtex-II Pro Platform FPGA Technology (All Devices): Updated number of differential standards supported from six to ten. • Section Input/Output Blocks (IOBs): Added text stating that differential termination is available for LVDS, LVDS Extended, ULVDS, and LDT standards. • Figure 1: Added note stating that -7 devices are not available in Industrial grade.
03/09/04	3.1.1	• Recompiled for backward compatibility with Acrobat 4 and above. No content changes.
06/30/04	4.0	Merged in DS110-1 (Module 1 of Virtex-II Pro X data sheet). Added information on available Pb-free packages.
11/17/04	4.1	*No changes in Module 1 for this revision.*
03/01/05	4.2	Table 3: Corrected number of RocketIO transceivers for XC2VP7-FG456.
06/20/05	4.3	*No changes in Module 1 for this revision.*
09/15/05	4.4	• Changed all instances of 10.3125 Gb/s (RocketIO transceiver maximum bit rate) to 6.25 Gb/s. • Changed all instances of 412.5 Gb/s (RocketIO X transceiver maximum multi-channel raw data transfer rate) to 250 Gb/s.
10/10/05	4.5	• Changed XC2VPX70 variable baud rate specification to fixed-rate operation at 4.25 Gb/s. • Changed maximum performance for -7 Virtex-II Pro X MGT (Table 4) to N/A.
03/05/07	4.6	*No changes in Module 1 for this revision.*
11/05/07	4.7	Updated copyright notice and legal disclaimer.
06/21/11	5.0	Added *Product Not Recommended for New Designs* banner.

Table 5: **Clock Ratios for Various Data Widths**

Fabric Data Width	Frequency Ratio of USRCLK:USRCLK2
1-byte	1:2 (1)
2-byte	1:1
4-byte	2:1 (1)

Notes:
1. Each edge of slower clock must align with falling edge of faster clock.

FPGA Transmit Interface

The FPGA can send either one, two, or four characters of data to the transmitter. Each character can be either 8 bits or 10 bits wide. If 8-bit data is applied, the additional inputs become control signals for the 8B/10B encoder. When the 8B/10B encoder is bypassed, the 10-bit character order is generated as follows:

TXCHARDISPMODE[0] (first bit transmitted)
TXCHARDISPVAL[0]
TXDATA[7:0] (last bit transmitted is TXDATA[0])

Disparity Control

The 8B/10B encoder is initialized with a negative running disparity. Unique control allows forcing the current running disparity state.

TXRUNDISP signals its current running disparity. This may be useful in those cases where there is a need to manipulate the initial running disparity value.

Bits TXCHARDISPMODE and TXCHARDISPVAL control the generation of running disparity before each byte.

For example, the transceiver can generate the sequence

```
K28.5+ K28.5+ K28.5- K28.5-
```

or

```
K28.5- K28.5- K28.5+ K28.5+
```

by specifying inverted running disparity for the second and fourth bytes.

Transmit FIFO

Proper operation of the circuit is only possible if the FPGA clock (TXUSRCLK) is frequency-locked to the reference clock (REFCLK). Phase variations up to one clock cycle are allowable. The FIFO has a depth of four. Overflow or underflow conditions are detected and signaled at the interface. Bypassing of this FIFO is programmable.

8B/10B Encoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

A bypassable 8B/10B encoder is included. The encoder uses the same 256 data characters and 12 control characters used by Gigabit Ethernet, Fibre Channel, and InfiniBand.

The encoder accepts 8 bits of data along with a K-character signal for a total of 9 bits per character applied, and generates a 10 bit character for transmission. If the K-character signal is High, the data is encoded into one of the twelve possible K-characters available in the 8B/10B code. If the K-character input is Low, the 8 bits are encoded as standard data. If the K-character input is High, and a user applies other than one of the twelve possible combinations, TXKERR indicates the error.

8B/10B Decoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

An optional 8B/10B decoder is included. A programmable option allows the decoder to be bypassed. When the 8B/10B decoder is bypassed, the 10-bit character order is, for example,

RXCHARISK[0] (first bit received)
RXRUNDISP[0]
RXDATA[7:0] (last bit received is RXDATA[0])

The decoder uses the same table that is used for Gigabit Ethernet, Fibre Channel, and InfiniBand. In addition to decoding all data and K-characters, the decoder has several extra features. The decoder separately detects both “disparity errors” and “out-of-band” errors. A disparity error is the reception of 10-bit character that exists within the 8B/10B table but has an incorrect disparity. An out-of-band error is the reception of a 10-bit character that does not exist within the 8B/10B table. It is possible to obtain an out-of-band error without having a disparity error. The proper disparity is always computed for both legal and illegal characters. The current running disparity is available at the RXRUNDISP signal.

The 8B/10B decoder performs a unique operation if out-of-band data is detected. If out-of-band data is detected, the decoder signals the error and passes the illegal 10-bits through and places them on the outputs. This can be used for debugging purposes if desired.

The decoder also signals the reception of one of the 12 valid K-characters. In addition, a programmable comma detect is included. The comma detect signal registers a comma on the receipt of any comma+, comma–, or both. Since the comma is defined as a 7-bit character, this includes several out-of-band characters. Another option allows the decoder to detect only the three defined commas (K28.1, K28.5, and K28.7) as comma+, comma–, or both. In total, there are six possible options, three for valid commas and three for "any comma."

Note that all bytes (1, 2, or 4) at the RX FPGA interface each have their own individual 8B/10B indicators (K-character, disparity error, out-of-band error, current running disparity, and comma detect).

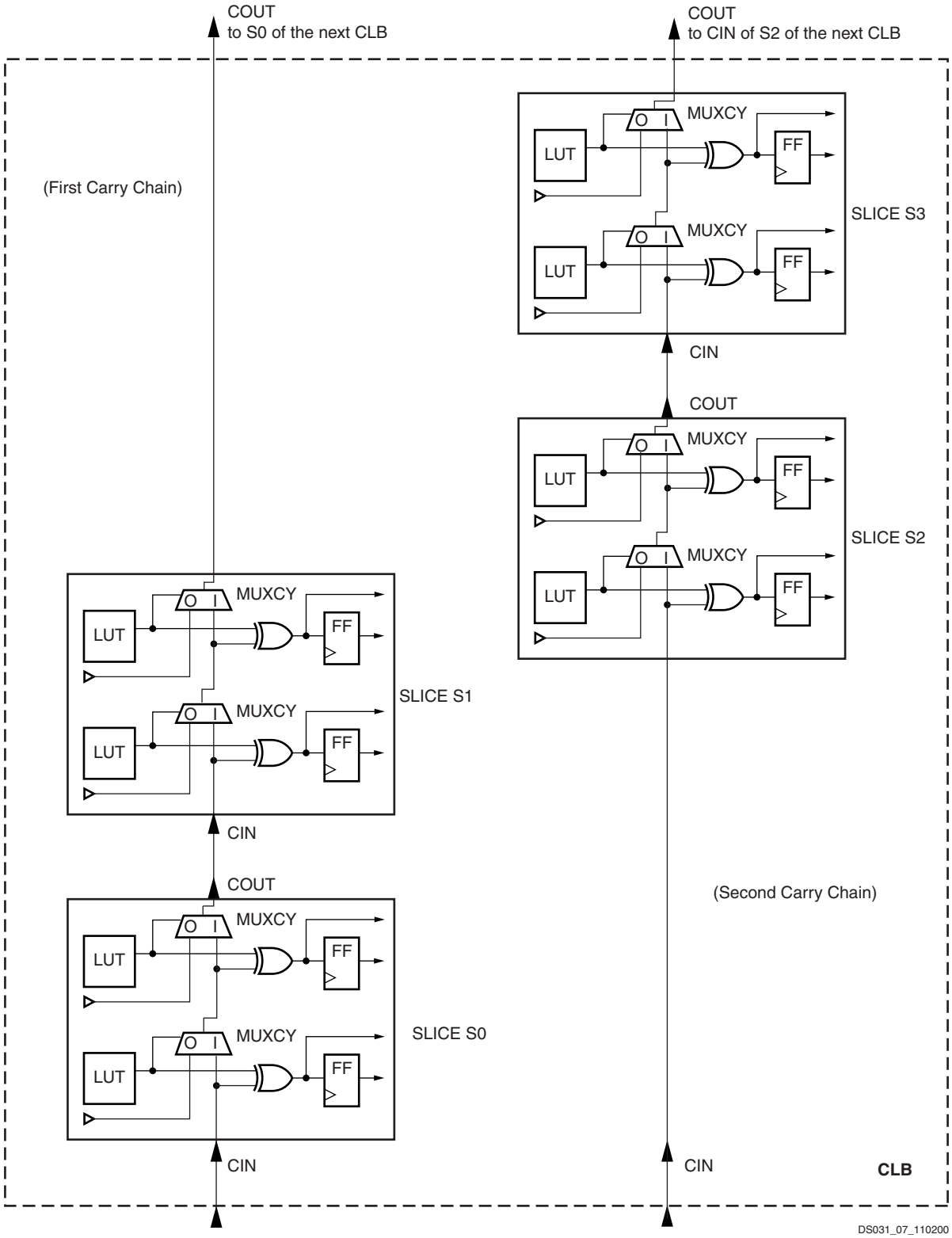

Figure 42: **Fast Carry Logic Path**

3. NO_CHANGE

The NO_CHANGE option maintains the content of the output registers, regardless of the write operation. The clock edge during the write mode has no effect on the content of the data output register DO. When the port is configured as NO_CHANGE, only a read operation loads a new value in the output register DO, as shown in Figure 51.

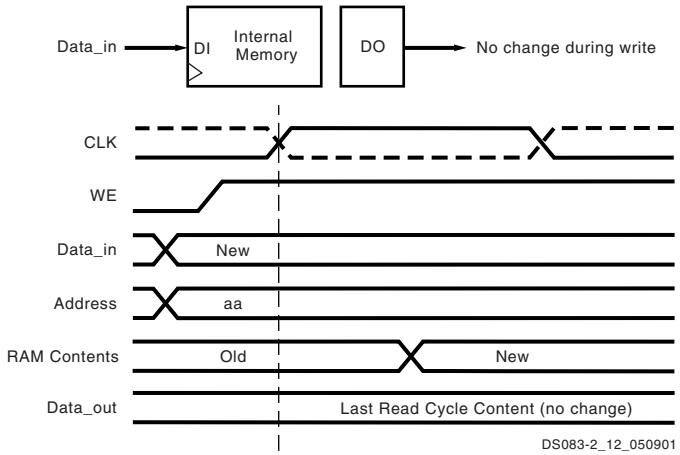

Figure 51: **NO_CHANGE Mode**

Control Pins and Attributes

Virtex-II Pro SelectRAM+ memory has two independent ports with the control signals described in Table 24. All control inputs including the clock have an optional inversion.

Table 24: **Control Functions**

Control Signal	Function
CLK	Read and Write Clock
EN	Enable affects Read, Write, Set, Reset
WE	Write Enable
SSR	Set DO register to SRVAL (attribute)

Initial memory content is determined by the INIT_xx attributes. Separate attributes determine the output register value after device configuration (INIT) and SSR is asserted (SRVAL). Both attributes (INIT_B and SRVAL) are available for each port when a block SelectRAM+ resource is configured as dual-port RAM.

Total Amount of SelectRAM+ Memory

Virtex-II Pro SelectRAM+ memory blocks are organized in multiple columns. The number of blocks per column depends on the row size, the number of Processor Blocks, and the number of RocketIO transceivers.

Table 25 shows the number of columns as well as the total amount of block SelectRAM+ memory available for each Virtex-II Pro device. The 18 Kb SelectRAM+ blocks are cascadable to implement deeper or wider single- or dual-port memory resources.

Table 25: **Virtex-II Pro SelectRAM+ Memory Available**

Device	Columns	Total SelectRAM+ Memory		
		Blocks	in Kb	in Bits
XC2VP2	4	12	216	221,184
XC2VP4	4	28	504	516,096
XC2VP7	6	44	792	811,008
XC2VP20	8	88	1,584	1,622,016
XC2VP30	8	136	2,448	2,506,752
XC2VPX20	8	88	1,584	1,622,016
XC2VP40	10	192	3,456	3,538,944
XC2VP50	12	232	4,176	4,276,224
XC2VP70	14	328	5,904	6,045,696
XC2VPX70	14	308	5,544	5,677,056
XC2VP100	16	444	7,992	8,183,808

Figure 52 shows the layout of the block RAM columns in the XC2VP4 device.

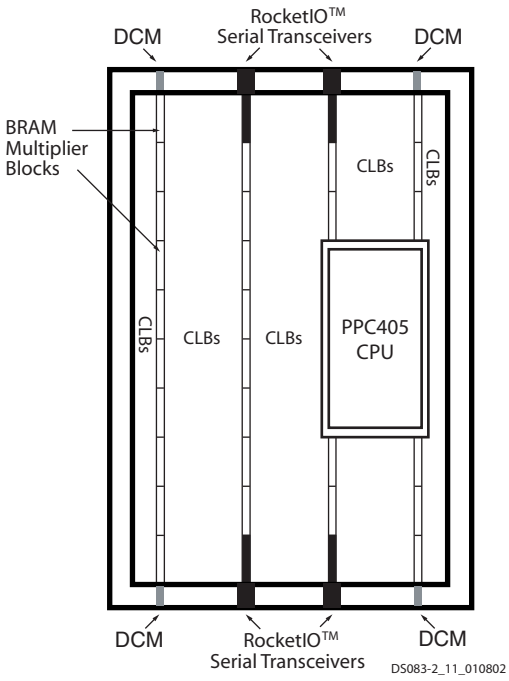

Figure 52: **XC2VP4 Block RAM Column Layout**

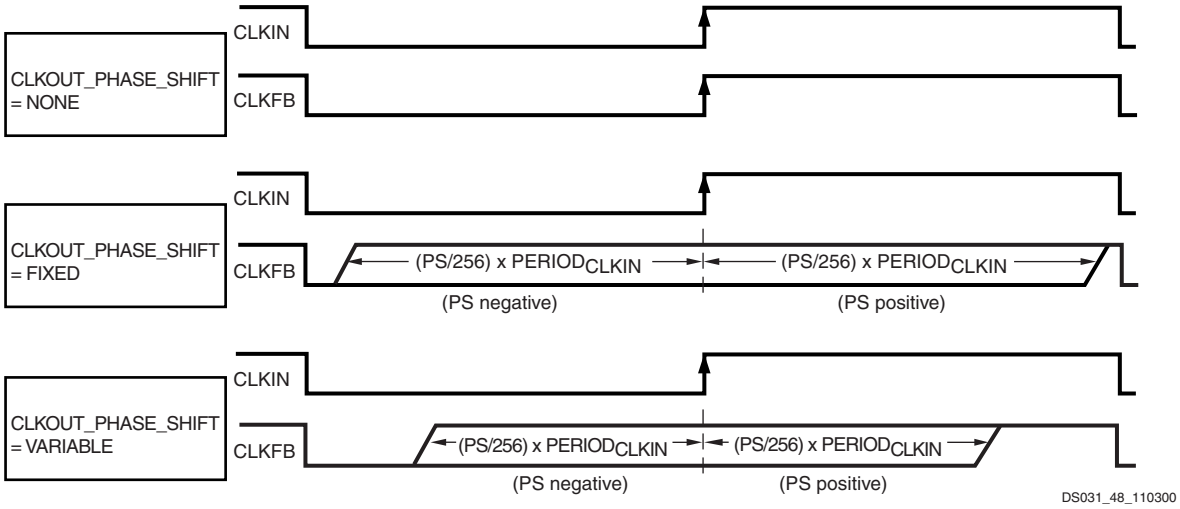

Figure 63: **Fine-Phase Shifting Effects**

Two separate components of the phase shift range must be understood:

- PHASE_SHIFT attribute range
- FINE_SHIFT_RANGE DCM timing parameter range

The PHASE_SHIFT attribute is the numerator in the following equation:

$$\text{Phase Shift (ns)} = (\text{PHASE\_SHIFT}/256) * \text{PERIOD}_{\text{CLKIN}}$$

The full range of this attribute is always -255 to +255, but its practical range varies with CLKIN frequency, as constrained by the FINE_SHIFT_RANGE component, which represents the total delay achievable by the phase shift delay line. Total delay is a function of the number of delay taps used in the circuit. Across process, voltage, and temperature, this absolute range is guaranteed to be as specified under **DCM Timing Parameters** in Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics.

Absolute range (fixed mode) = ± FINE_SHIFT_RANGE

Absolute range (variable mode) = ± FINE_SHIFT_RANGE/2

The reason for the difference between fixed and variable modes is as follows. For variable mode to allow symmetric, dynamic sweeps from -255/256 to +255/256, the DCM sets the "zero phase skew" point as the middle of the delay line, thus dividing the total delay line range in half. In fixed mode, since the PHASE_SHIFT value never changes after configuration, the entire delay line is available for insertion into either the CLKIN or CLKFB path (to create either positive or negative skew).

Taking both of these components into consideration, the following are some usage examples:

- If $\text{PERIOD}_{\text{CLKIN}} = 2 * \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 128, and in variable mode it is limited to ± 64.
- If $\text{PERIOD}_{\text{CLKIN}} = \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT in fixed mode is limited to ± 255, and in variable mode it is limited to ± 128.
- If $\text{PERIOD}_{\text{CLKIN}} \leq 0.5 * \text{FINE\_SHIFT\_RANGE}$, then PHASE_SHIFT is limited to ± 255 in either mode.

Operating Modes

The frequency ranges of DCM input and output clocks depend on the operating mode specified, either low-frequency mode or high-frequency mode, according to Table 30. For actual values, see Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics. The CLK2X, CLK2X180, CLK90, and CLK270 outputs are not available in high-frequency mode.

High or low-frequency mode is selected by an attribute.

Table 30: **DCM Frequency Ranges**

Output Clock	Low-Frequency Mode		High-Frequency Mode	
	CLKIN Input	CLK Output	CLKIN Input	CLK Output
CLK0, CLK180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_1X_HF
CLK90, CLK270	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_1X_LF	NA	NA
CLK2X, CLK2X180	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_2X_LF	NA	NA
CLKDV	CLKIN_FREQ_DLL_LF	CLKOUT_FREQ_DV_LF	CLKIN_FREQ_DLL_HF	CLKOUT_FREQ_DV_HF
CLKFX, CLKFX180	CLKIN_FREQ_FX_LF	CLKOUT_FREQ_FX_LF	CLKIN_FREQ_FX_HF	CLKOUT_FREQ_FX_HF

- The double lines route signals to every first or second block away in all four directions. Organized in a staggered pattern, double lines can be driven only at their endpoints. Double-line signals can be accessed either at the endpoints or at the midpoint (one block from the source).
- The direct connect lines route signals to neighboring blocks: vertically, horizontally, and diagonally.
- The fast connect lines are the internal CLB local interconnections from LUT outputs to LUT inputs.

Dedicated Routing

In addition to the global and local routing resources, dedicated signals are available.

- There are eight global clock nets per quadrant. (See Global Clock Multiplexer Buffers, page 48.)
- Horizontal routing resources are provided for on-chip 3-state buses. Four partitionable bus lines are provided per CLB row, permitting multiple buses within a row. (See 3-State Buffers, page 43.)
- Two dedicated carry-chain resources per slice column (two per CLB column) propagate carry-chain MUXCY output signals vertically to the adjacent slice. (See CLB/Slice Configurations, page 44.)
- One dedicated SOP chain per slice row (two per CLB row) propagate ORCY output logic signals horizontally to the adjacent slice. (See Sum of Products, page 42.)
- One dedicated shift-chain per CLB connects the output of LUTs in shift-register mode to the input of the next LUT in shift-register mode (vertically) inside the CLB. (See Shift Registers, page 39.)

Virtex-II Pro and Virtex-II Pro X Platform FPGAs: DC and Switching Characteristics

DS083 (v5.0) June 21, 2011 **Product Specification**

Virtex-II Pro[1] Electrical Characteristics

Virtex™-II Pro devices are provided in -7, -6, and -5 speed grades, with -7 having the highest performance.

Virtex-II Pro DC and AC characteristics are specified for both commercial and industrial grades. Except the operating temperature range or unless otherwise noted, all the DC and AC electrical parameters are the same for a particular speed grade (that is, the timing characteristics of a -6 speed grade industrial device are the same as for a -6 speed grade commercial device). However, only selected speed grades and/or devices might be available in the industrial range.

All supply voltage and junction temperature specifications are representative of worst-case conditions. The parameters included are common to popular designs and typical applications. Contact Xilinx for design considerations requiring more detailed information.

All specifications are subject to change without notice.

Virtex-II Pro DC Characteristics

Table 1: **Absolute Maximum Ratings**

Symbol	Description[1]		Virtex-II Pro X	Virtex-II Pro	Units
V_{CCINT}	Internal supply voltage relative to GND		–0.5 to 1.6		V
V_{CCAUX}	Auxiliary supply voltage relative to GND		–0.5 to 3.0		V
V_{CCO}	Output drivers supply voltage relative to GND		–0.5 to 3.75		V
V_{BATT}	Key memory battery backup supply		–0.5 to 4.05		V
V_{REF}	Input reference voltage		–0.3 to 3.75		V
V_{IN}	3.3V I/O input voltage relative to GND (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	2.5V or below I/O input voltage relative to GND (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
V_{TS}	Voltage applied to 3-state 3.3V output (user and dedicated I/Os)		–0.3 to 4.05[3]		V
	Voltage applied to 3-state 2.5V or below output (user and dedicated I/Os)		–0.5 to V_{CCO} + 0.5		V
AVCCAUXRX	Receive auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 2.0	–0.5 to 3.0	V
AVCCAUXTX	Transmit auxilliary supply voltage relative to GNDA (analog ground)		–0.5 to 3.0	–0.5 to 3.0	V
V_{TRX}	Terminal receive supply voltage relative to GND		–0.5 to 3.0	–0.5 to 3.0	V
V_{TTX}	Terminal transmit supply voltage relative to GND		–0.5 to 1.6	–0.5 to 3.0	V
T_{STG}	Storage temperature (ambient)		–65 to +150		°C
T_{SOL}	Maximum soldering temperature[2]	All regular FG/FF flip-chip packages	+220		°C
		Pb-free FGG256 wire-bond package	N/A	+260	°C
		Pb-free FGG456 and FGG676 wire-bond packages	N/A	+250	°C
T_J	Maximum junction temperature[2]		+125		°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings might cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time might affect device reliability.
2. For soldering guidelines and thermal considerations, see the **Device Packaging and Thermal Characteristics Guide** information on the Xilinx website.
3. 3.3V I/O Absolute Maximum limit applied to DC and AC signals. Refer to **XAPP659** for more details.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

© 2000–2011 Xilinx, Inc. All rights reserved. XILINX, the Xilinx logo, the Brand Window, and other designated brands included herein are trademarks of Xilinx, Inc. PowerPC is a trademark of IBM Corp. and is used under license. All other trademarks are the property of their respective owners.

RocketIO Switching Characteristics

Table 22: **RocketIO X Reference Clock Switching Characteristics**

			All Speed Grades			
Description	**Symbol**	**Conditions**	**Min**	**Typ**	**Max**	**Units**
Reference Clock frequency range(1)	F_{GCLK}		62.5		425	MHz
Reference Clock frequency tolerance	F_{GTOL}				±350	ppm
Reference Clock rise time	T_{RCLK}	20% – 80%		75		ps
Reference Clock fall time	T_{FCLK}	20% – 80%		75		ps
Reference Clock duty cycle	T_{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak	T_{GJTT}	3.125 Gb/s – 6.25 Gb/s			30	ps
		2.488 Gb/s – 3.125 Gb/s			40	ps
Clock recovery frequency acquisition time, from Power-up to High state of PMARXLOCK	T_{LOCK}			100		µs
Clock recovery phase acquisition time, from Data to High state of PMARXLOCK	T_{PHASE}			40	60	µs

Notes:
1. BREFCLK should be used for all serial bit rates up to the maximum shown.

Table 23: **RocketIO Reference Clock Switching Characteristics**

			All Speed Grades			
Description	**Symbol**	**Conditions**	**Min**	**Typ**	**Max**	**Units**
Reference Clock frequency range(1)	F_{GCLK}	Full rate operation	50		156.25	MHz
		Half rate operation(2) (2X oversampling)	60		100	MHz
Reference Clock frequency tolerance	F_{GTOL}				±100	ppm
Reference Clock rise time	T_{RCLK}	20% – 80%		600	1000	ps
Reference Clock fall time	T_{FCLK}	20% – 80%		600	1000	ps
Reference Clock duty cycle	T_{DCREF}		45	50	55	%
Reference Clock total jitter, peak-peak(3)	T_{GJTT}	2.501 Gb/s – 3.125 Gb/s			40	ps
		1.061 Gb/s – 2.5 Gb/s			50	ps
		< 1.06 Gb/s			120	ps
Clock recovery frequency acquisition time	T_{LOCK}				10	µs
Clock recovery phase acquisition time	T_{PHASE}			960		bits(4)

Notes:
1. BREFCLK/BREFCLK2 can be used for all serial bit rates up to the maximum shown. REFCLK/REFCLK2 can be used for serial bit rates up to 2.5 Gb/s (REFCLK = 125 MHz). All other parameters apply equally to REFCLK, REFCLK2, BREFCLK, and BREFCLK2 except as noted.
2. For serial rates under 1 Gb/s, the 3X (or greater) oversampling techniques described in **XAPP572** are required to meet the transmit jitter and receive jitter tolerance specifications defined in this data sheet.
3. Measured at the package pin. For reference clock frequencies equal to or above 125 MHz, BREFCLK/BREFCLK2 must be used.
4. 8B/10B-type bitstream.

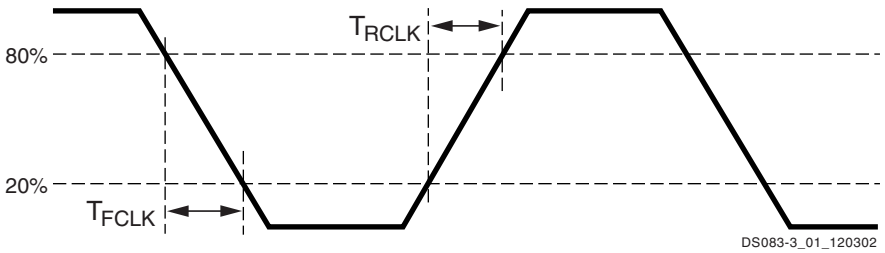

Figure 3: **Reference Clock Timing Parameters**

Table 38: **IOB Output Switching Characteristics Standard Adjustments *(Continued)***

Description	IOSTANDARD Attribute	Timing Parameter	Speed Grade			Units
			-7	-6	-5	
HSTL, Class II	HSTL_II	T_{OHSTL_II}	0.30	0.35	0.38	ns
HSTL, Class III	HSTL_III	T_{OHSTL_IIII}	0.31	0.35	0.39	ns
HSTL, Class IV	HSTL_IV	T_{OHSTL_IV}	0.15	0.17	0.19	ns
HSTL, Class I, 1.8V	HSTL_I_18	$T_{OHSTL\_I\_18}$	0.56	0.64	0.70	ns
HSTL, Class II, 1.8V	HSTL_II_18	$T_{OHSTL\_II\_18}$	0.30	0.35	0.38	ns
HSTL, Class III, 1.8V	HSTL_III_18	$T_{OHSTL\_IIII\_18}$	0.36	0.41	0.45	ns
HSTL, Class IV, 1.8V	HSTL_IV_18	$T_{OHSTL\_IV\_18}$	0.19	0.22	0.24	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	$T_{OSSTL18\_I}$	0.80	0.92	1.01	ns
SSTL, Class II, 1.8V	SSTL18_II	$T_{OSSTL18\_II}$	0.45	0.51	0.56	ns
SSTL, Class I, 2.5V	SSTL2_I	T_{OSSTL2_I}	0.63	0.72	0.79	ns
SSTL, Class II, 2.5V	SSTL2_II	T_{OSSTL2_II}	0.22	0.25	0.27	ns
LVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	T_{OLVDCI_33}	0.72	0.83	0.91	ns
LVDCI, 2.5V	LVDCI_25	T_{OLVDCI_25}	0.56	0.64	0.71	ns
LVDCI, 1.8V	LVDCI_18	T_{OLVDCI_18}	0.65	0.75	0.82	ns
LVDCI, 1.5V	LVDCI_15	T_{OLVDCI_15}	1.00	1.15	1.26	ns
LVDCI, 2.5V, Half-Impedance	LVDCI_DV2_25	$T_{OLVDCI\_DV2\_25}$	0.06	0.07	0.08	ns
LVDCI, 1.8V, Half-Impedance	LVDCI_DV2_18	$T_{OLVDCI\_DV2\_18}$	0.30	0.34	0.38	ns
LVDCI, 1.5V, Half-Impedance	LVDCI_DV2_15	$T_{OLVDCI\_DV2\_15}$	0.60	0.69	0.76	ns
HSLVDCI (High-Speed Low-Voltage DCI), 1.5V	HSLVDCI_15	$T_{OHSLVDCI\_15}$	1.00	1.15	1.26	ns
HSLVDCI, 1.8V	HSLVDCI_18	$T_{OHSLVDCI\_18}$	0.65	0.75	0.82	ns
HSLVDCI, 2.5V	HSLVDCI_25	$T_{OHSLVDCI\_25}$	0.56	0.64	0.71	ns
HSLVDCI, 3.3V	HSLVDCI_33	$T_{OHSLVDCI\_33}$	0.72	0.83	0.91	ns
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	T_{OGTL_DCI}	1.21	1.39	1.53	ns
GTL Plus with DCI	GTLP_DCI	T_{OGTLP_DCI}	0.05	0.06	0.07	ns
HSTL (High-Speed Transceiver Logic), Class I, with DCI	HSTL_I_DCI	$T_{OHSTL\_I\_DCI}$	0.55	0.63	0.69	ns
HSTL, Class II, with DCI	HSTL_II_DCI	$T_{OHSTL\_II\_DCI}$	0.47	0.54	0.60	ns
HSTL, Class III, with DCI	HSTL_III_DCI	$T_{OHSTL\_III\_DCI}$	0.31	0.36	0.40	ns
HSTL, Class IV, with DCI	HSTL_IV_DCI	$T_{OHSTL\_IV\_DCI}$	1.81	2.08	2.29	ns
HSTL, Class I, 1.8V, with DCI	HSTL_I_DCI_18	$T_{OHSTL\_I\_DCI\_18}$	0.55	0.63	0.70	ns
HSTL, Class II, 1.8V, with DCI	HSTL_II_DCI_18	$T_{OHSTL\_II\_DCI\_18}$	0.24	0.28	0.31	ns
HSTL, Class III, 1.8V, with DCI	HSTL_III_DCI_18	$T_{OHSTL\_III\_DCI\_18}$	0.35	0.40	0.44	ns
HSTL, Class IV, 1.8V, with DCI	HSTL_IV_DCI_18	$T_{OHSTL\_IV\_DCI\_18}$	1.48	1.70	1.87	ns
SSTL (Stub Series Terminated Logic), Class I, 1.8V, with DCI	SSTL18_I_DCI	$T_{OSSTL18\_I\_DCI}$	0.54	0.62	0.68	ns
SSTL, Class II, 1.8V, with DCI	SSTL18_II_DCI	$T_{OSSTL18\_II\_DCI}$	0.24	0.28	0.31	ns
SSTL, Class I, 2.5V, with DCI	SSTL2_I_DCI	$T_{OSSTL2\_I\_DCI}$	0.48	0.56	0.61	ns
SSTL, Class II, 2.5V, with DCI	SSTL2_II_DCI	$T_{OSSTL2\_II\_DCI}$	0.48	0.56	0.61	ns

Table 40: **Output Delay Measurement Methodology**

Description	IOSTANDARD Attribute	R_{REF} (Ω)	C_{REF}[1] (pF)	V_{MEAS} (V)	V_{REF} (V)
SSTL (Stub Series Terminated Logic), Class I, 1.8V	SSTL18_I	50	0	V_{REF}	0.9
SSTL, Class II, 1.8V	SSTL18_II	25	0	V_{REF}	0.9
SSTL, Class I, 2.5V	SSTL2_I	50	0	V_{REF}	1.25
SSTL, Class II, 2.5V	SSTL2_II	25	0	V_{REF}	1.25
LVDS (Low-Voltage Differential Signaling), 2.5V	LVDS_25	50	0	V_{REF}	1.2
LVDSEXT (LVDS Extended Mode), 2.5V	LVDSEXT_25	50	0	V_{REF}	1.2
BLVDS (Bus LVDS), 2.5V	BLVDS_25	1M	0	1.2	0
LDT (HyperTransport), 2.5V	LDT_25	50	0	V_{REF}	0.6
LVPECL (Low-Voltage Positive Emitter-Coupled Logic), 2.5V	LVPECL_25	1M	0	1.23	0
LVDCI/HSLVDCI (Low-Voltage Digitally Controlled Impedance), 3.3V	LVDCI_33	1M	0	1.65	0
LVDCI/HSLVDCI, 2.5V	LVDCI_25	1M	0	1.25	0
LVDCI/HSLVDCI, 1.8V	LVDCI_18	1M	0	0.9	0
LVDCI/HSLVDCI, 1.5V	LVDCI_15	1M	0	0.75	0
HSTL (High-Speed Transceiver Logic), Class I & II, with DCI	HSTL_I_DCI, HSTL_II_DCI	50	0	V_{REF}	0.75
HSTL, Class III & IV, with DCI	HSTL_III_DCI, HSTL_IV_DCI	50	0	0.9	1.5
HSTL, Class I & II, 1.8V, with DCI	HSTL_I_DCI_18, HSTL_II_DCI_18	50	0	V_{REF}	0.9
HSTL, Class III & IV, 1.8V, with DCI	HSTL_III_DCI_18, HSTL_IV_DCI_18	50	0	1.1	1.8
SSTL (Stub Series Termi.Logic), Class I & II, 1.8V, with DCI	SSTL18_I_DCI, SSTL18_II_DCI	50	0	V_{REF}	0.9
SSTL, Class I & II, 2.5V, with DCI	SSTL2_I_DCI, SSTL2_II_DCI	50	0	V_{REF}	1.25
GTL (Gunning Transceiver Logic) with DCI	GTL_DCI	50	0	0.8	1.2
GTL Plus with DCI	GTLP_DCI	50	0	1.0	1.5

Notes:
1. C_{REF} is the capacitance of the probe, nominally 0 pF.
2. Measured as per PCI specification.
3. Measured as per PCI-X specification.

Multiplier Switching Characteristics

Table 45: **Multiplier Switching Characteristics**

Description	Symbol	Speed Grade			Units
		-7	-6	-5	
Propagation Delay to Output Pin					
Input to Pin35	T_{MULT_P35}	4.08	4.64	5.19	ns, max
Input to Pin34	T_{MULT_P34}	3.99	4.55	5.09	ns, max
Input to Pin33	T_{MULT_P33}	3.90	4.45	4.99	ns, max
Input to Pin32	T_{MULT_P32}	3.80	4.36	4.88	ns, max
Input to Pin31	T_{MULT_P31}	3.71	4.27	4.78	ns, max
Input to Pin30	T_{MULT_P30}	3.62	4.17	4.67	ns, max
Input to Pin29	T_{MULT_P29}	3.53	4.08	4.57	ns, max
Input to Pin28	T_{MULT_P28}	3.43	3.99	4.46	ns, max
Input to Pin27	T_{MULT_P27}	3.34	3.89	4.36	ns, max
Input to Pin26	T_{MULT_P26}	3.25	3.80	4.26	ns, max
Input to Pin25	T_{MULT_P25}	3.16	3.71	4.15	ns, max
Input to Pin24	T_{MULT_P24}	3.06	3.61	4.05	ns, max
Input to Pin23	T_{MULT_P23}	2.97	3.52	3.94	ns, max
Input to Pin22	T_{MULT_P22}	2.88	3.43	3.84	ns, max
Input to Pin21	T_{MULT_P21}	2.79	3.34	3.73	ns, max
Input to Pin20	T_{MULT_P20}	2.70	3.24	3.63	ns, max
Input to Pin19	T_{MULT_P19}	2.60	3.15	3.53	ns, max
Input to Pin18	T_{MULT_P18}	2.51	3.06	3.42	ns, max
Input to Pin17	T_{MULT_P17}	2.42	2.96	3.32	ns, max
Input to Pin16	T_{MULT_P16}	2.34	2.86	3.21	ns, max
Input to Pin15	T_{MULT_P15}	2.27	2.76	3.09	ns, max
Input to Pin14	T_{MULT_P14}	2.19	2.67	2.98	ns, max
Input to Pin13	T_{MULT_P13}	2.12	2.57	2.87	ns, max
Input to Pin12	T_{MULT_P12}	2.04	2.47	2.76	ns, max
Input to Pin11	T_{MULT_P11}	1.96	2.37	2.65	ns, max
Input to Pin10	T_{MULT_P10}	1.89	2.27	2.54	ns, max
Input to Pin9	T_{MULT_P9}	1.81	2.17	2.43	ns, max
Input to Pin8	T_{MULT_P8}	1.74	2.07	2.32	ns, max
Input to Pin7	T_{MULT_P7}	1.66	1.97	2.21	ns, max
Input to Pin6	T_{MULT_P6}	1.59	1.87	2.09	ns, max
Input to Pin5	T_{MULT_P5}	1.51	1.77	1.98	ns, max
Input to Pin4	T_{MULT_P4}	1.44	1.67	1.87	ns, max
Input to Pin3	T_{MULT_P3}	1.36	1.57	1.76	ns, max
Input to Pin2	T_{MULT_P2}	1.28	1.47	1.65	ns, max
Input to Pin1	T_{MULT_P1}	1.21	1.37	1.54	ns, max
Input to Pin0	T_{MULT_P0}	1.13	1.27	1.43	ns, max

Virtex-II Pro Pin-to-Pin Input Parameter Guidelines

All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted

Global Clock Set-Up and Hold for LVCMOS25 Standard, *With* DCM

Table 55: **Global Clock Set-Up and Hold for LVCMOS25 Standard, *With* DCM**

			Speed Grade			
Description	**Symbol**	**Device**	**-7**	**-6**	**-5**	**Units**
Input Setup and Hold Time Relative to Global Clock Input Signal for LVCMOS25 Standard.(1) For data input with different standards, adjust the setup time delay by the values shown in IOB Input Switching Characteristics Standard Adjustments, page 25.						
No Delay Global Clock and IFF(2) with DCM	T_{PSDCM}/T_{PHDCM}	XC2VP2	1.54/–0.58	1.54/–0.57	1.54/–0.56	ns
		XC2VP4	1.59/–0.59	1.59/–0.58	1.59/–0.57	ns
		XC2VP7	1.66/–0.61	1.66/–0.59	1.66/–0.57	ns
		XC2VP20	1.68/–0.53	1.68/–0.53	1.68/–0.50	ns
		XC2VPX20	1.68/–0.53	1.68/–0.53	1.68/–0.50	ns
		XC2VP30	1.81/–0.74	1.81/–0.74	1.81/–0.71	ns
		XC2VP40	1.85/–0.65	1.85/–0.64	1.85/–0.60	ns
		XC2VP50	1.85/–0.57	1.85/–0.54	1.85/–0.50	ns
		XC2VP70	1.86/–0.45	1.86/–0.39	1.86/–0.30	ns
		XC2VPX70	1.86/–0.45	1.86/–0.39	1.86/–0.30	ns
		XC2VP100	N/A	1.86/–0.35	1.87/–0.28	ns

Notes:

1. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
2. These measurements include:
   - CLK0 and CLK180 DCM jitter
   - Worst-case duty-cycle distortion using CLK0 and CLK180, T_{DCD_CLK180}.
3. IFF = Input Flip-Flop or Latch

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
N/A	GND	R15			
N/A	GND	R16			
N/A	GND	R17			
N/A	GND	T11			
N/A	GND	T12			
N/A	GND	T13			
N/A	GND	T14			
N/A	GND	T15			
N/A	GND	T16			
N/A	GND	U10			
N/A	GND	U12			
N/A	GND	U13			
N/A	GND	U14			
N/A	GND	U15			
N/A	GND	U17			
N/A	GND	Y20			
N/A	GND	AA21			
N/A	GND	AB22			
N/A	GND	AC23			
N/A	GND	AD24			

Notes:
1. See Table 4 for an explanation of the signals available on this pin.

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
4	VCCO_4		AA11			
4	VCCO_4		AA10			
5	VCCO_5		AB21			
5	VCCO_5		AB20			
5	VCCO_5		AB19			
5	VCCO_5		AB18			
5	VCCO_5		AA21			
5	VCCO_5		AA20			
5	VCCO_5		AA19			
5	VCCO_5		AA18			
5	VCCO_5		AA17			
5	VCCO_5		AA16			
6	VCCO_6		AB22			
6	VCCO_6		AA22			
6	VCCO_6		Y22			
6	VCCO_6		Y21			
6	VCCO_6		W22			
6	VCCO_6		W21			
6	VCCO_6		V22			
6	VCCO_6		V21			
6	VCCO_6		U21			
6	VCCO_6		T21			
7	VCCO_7		R21			
7	VCCO_7		P21			
7	VCCO_7		N22			
7	VCCO_7		N21			
7	VCCO_7		M22			
7	VCCO_7		M21			
7	VCCO_7		L22			
7	VCCO_7		L21			
7	VCCO_7		K22			
7	VCCO_7		J22			
N/A	CCLK		AC7			
N/A	PROG_B		G24			
N/A	DONE		AC8			

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
3	IO_L39P_3	AD4				
3	IO_L38N_3	AB9				
3	IO_L38P_3	AB10				
3	IO_L37N_3	AD5				
3	IO_L37P_3	AD6				
3	IO_L36N_3	AE2				
3	IO_L36P_3	AF2				
3	IO_L35N_3	AD7				
3	IO_L35P_3	AD8				
3	IO_L34N_3	AE4				
3	IO_L34P_3	AE5				
3	IO_L33N_3/VREF_3	AG1				
3	IO_L33P_3	AG2				
3	IO_L32N_3	AC9				
3	IO_L32P_3	AC10				
3	IO_L31N_3	AF3				
3	IO_L31P_3	AF4				
3	IO_L24N_3	AH1	NC			
3	IO_L24P_3	AH2	NC			
3	IO_L23N_3	AE7	NC			
3	IO_L23P_3	AE8	NC			
3	IO_L22N_3	AF5	NC			
3	IO_L22P_3	AF6	NC			
3	IO_L21N_3/VREF_3	AG3	NC			
3	IO_L21P_3	AG4	NC			
3	IO_L20N_3	AD9	NC			
3	IO_L20P_3	AD10	NC			
3	IO_L19N_3	AH3	NC			
3	IO_L19P_3	AH4	NC			
3	IO_L18N_3	AJ1	NC			
3	IO_L18P_3	AJ2	NC			
3	IO_L17N_3	AF7	NC			
3	IO_L17P_3	AF8	NC			
3	IO_L16N_3	AK1	NC			
3	IO_L16P_3	AK2	NC			
3	IO_L15N_3/VREF_3	AG5	NC			
3	IO_L15P_3	AG6	NC			
3	IO_L06N_3	AL1				

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
0	IO_L59P_0	N21		
0	IO_L60N_0	E23		
0	IO_L60P_0	F22		
0	IO_L64N_0	D22		
0	IO_L64P_0	E22		
0	IO_L65N_0	H21		
0	IO_L65P_0	H20		
0	IO_L66N_0	G22		
0	IO_L66P_0/VREF_0	G21		
0	IO_L67N_0	D21		
0	IO_L67P_0	E21		
0	IO_L68N_0	J21		
0	IO_L68P_0	K21		
0	IO_L69N_0	C22		
0	IO_L69P_0/VREF_0	C21		
0	IO_L73N_0	F21		
0	IO_L73P_0	F20		
0	IO_L74N_0/GCLK7P	L21		
0	IO_L74P_0/GCLK6S	M21		
0	IO_L75N_0/GCLK5P	D20		
0	IO_L75P_0/GCLK4S	E20		
1	IO_L75N_1/GCLK3P	K20		
1	IO_L75P_1/GCLK2S	J20		
1	IO_L74N_1/GCLK1P	N20		
1	IO_L74P_1/GCLK0S	M20		
1	IO_L73N_1	E19		
1	IO_L73P_1	D19		
1	IO_L69N_1/VREF_1	G19		
1	IO_L69P_1	F19		
1	IO_L68N_1	L19		
1	IO_L68P_1	K19		
1	IO_L67N_1	J19		
1	IO_L67P_1	H19		
1	IO_L66N_1/VREF_1	C19		
1	IO_L66P_1	C18		
1	IO_L65N_1	N19		
1	IO_L65P_1	M19		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
0	IO_L34N_0		E30		
0	IO_L34P_0		F30		
0	IO_L35N_0		D30		
0	IO_L35P_0		C30		
0	IO_L36N_0		M28		
0	IO_L36P_0/VREF_0		M29		
0	IO_L78N_0		K29	NC	
0	IO_L78P_0		L29	NC	
0	IO_L83_0/No_Pair		H29	NC	
0	IO_L84N_0		F29	NC	
0	IO_L84P_0		G29	NC	
0	IO_L85N_0		D29	NC	
0	IO_L85P_0		E29	NC	
0	IO_L86N_0		L28	NC	
0	IO_L86P_0		K28	NC	
0	IO_L87N_0		H28	NC	
0	IO_L87P_0/VREF_0		J28	NC	
0	IO_L37N_0		E28		
0	IO_L37P_0		F28		
0	IO_L38N_0		C29		
0	IO_L38P_0		C28		
0	IO_L39N_0		L27		
0	IO_L39P_0		M27		
0	IO_L43N_0		J27		
0	IO_L43P_0		K27		
0	IO_L44N_0		H27		
0	IO_L44P_0		G27		
0	IO_L45N_0		E27		
0	IO_L45P_0/VREF_0		F27		
0	IO_L46N_0		M25		
0	IO_L46P_0		M26		
0	IO_L47N_0		L26		
0	IO_L47P_0		K26		
0	IO_L48N_0		H26		
0	IO_L48P_0		J26		
0	IO_L49N_0		F26		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
4	IO_L60P_4		AR19		
4	IO_L64N_4		AV19		
4	IO_L64P_4		AU19		
4	IO_L65N_4		AW19		
4	IO_L65P_4		AY19		
4	IO_L66N_4		AL21		
4	IO_L66P_4/VREF_4		AL20		
4	IO_L67N_4		AN20		
4	IO_L67P_4		AM20		
4	IO_L68N_4		AP20		
4	IO_L68P_4		AR20		
4	IO_L69N_4		AV20		
4	IO_L69P_4/VREF_4		AU20		
4	IO_L73N_4		AY20		
4	IO_L73P_4		AW20		
4	IO_L74N_4/GCLK3S		AN21		
4	IO_L74P_4/GCLK2P		AP21		
4	IO_L75N_4/GCLK1S		AU21		
4	IO_L75P_4/GCLK0P		AT21		
5	IO_L75N_5/GCLK7S	BREFCLKN	AT22		
5	IO_L75P_5/GCLK6P	BREFCLKP	AU22		
5	IO_L74N_5/GCLK5S		AP22		
5	IO_L74P_5/GCLK4P		AN22		
5	IO_L73N_5		AW23		
5	IO_L73P_5		AY23		
5	IO_L69N_5/VREF_5		AU23		
5	IO_L69P_5		AV23		
5	IO_L68N_5		AR23		
5	IO_L68P_5		AP23		
5	IO_L67N_5		AM23		
5	IO_L67P_5		AN23		
5	IO_L66N_5/VREF_5		AL23		
5	IO_L66P_5		AL22		
5	IO_L65N_5		AY24		
5	IO_L65P_5		AW24		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
7	IO_L87P_7		AA33		
7	IO_L87N_7		AA34		
7	IO_L86P_7		Y31		
7	IO_L86N_7		Y32		
7	IO_L85P_7		Y39		
7	IO_L85N_7		Y40		
7	IO_L60P_7		Y36		
7	IO_L60N_7		Y37		
7	IO_L59P_7		Y33		
7	IO_L59N_7		Y34		
7	IO_L58P_7		W41		
7	IO_L58N_7/VREF_7		W42		
7	IO_L57P_7		W39		
7	IO_L57N_7		W40		
7	IO_L56P_7		W31		
7	IO_L56N_7		W32		
7	IO_L55P_7		W37		
7	IO_L55N_7		W38		
7	IO_L54P_7		W35		
7	IO_L54N_7		W36		
7	IO_L53P_7		W33		
7	IO_L53N_7		W34		
7	IO_L52P_7		V41		
7	IO_L52N_7/VREF_7		V42		
7	IO_L51P_7		V38		
7	IO_L51N_7		V39		
7	IO_L50P_7		V31		
7	IO_L50N_7		U32		
7	IO_L49P_7		V35		
7	IO_L49N_7		V36		
7	IO_L48P_7		V32		
7	IO_L48N_7		V33		
7	IO_L47P_7		U31		
7	IO_L47N_7		T31		
7	IO_L46P_7		U41		
7	IO_L46N_7/VREF_7		U42		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
7	IO_L26P_7	V31	
7	IO_L26N_7	U31	
7	IO_L25P_7	L41	
7	IO_L25N_7	L42	
7	IO_L24P_7	K40	
7	IO_L24N_7	L40	
7	IO_L23P_7	T34	
7	IO_L23N_7	T35	
7	IO_L22P_7	L38	
7	IO_L22N_7/VREF_7	L39	
7	IO_L21P_7	K36	
7	IO_L21N_7	L36	
7	IO_L20P_7	T32	
7	IO_L20N_7	T33	
7	IO_L19P_7	K41	
7	IO_L19N_7	K42	
7	IO_L18P_7	K37	
7	IO_L18N_7	K38	
7	IO_L17P_7	R34	
7	IO_L17N_7	R35	
7	IO_L16P_7	H42	
7	IO_L16N_7/VREF_7	J41	
7	IO_L15P_7	J39	
7	IO_L15N_7	J40	
7	IO_L14P_7	R32	
7	IO_L14N_7	R33	
7	IO_L13P_7	J36	
7	IO_L13N_7	J37	
7	IO_L12P_7	H40	
7	IO_L12N_7	H41	
7	IO_L11P_7	T31	
7	IO_L11N_7	R31	
7	IO_L10P_7	H38	
7	IO_L10N_7/VREF_7	H39	
7	IO_L09P_7	H36	
7	IO_L09N_7	H37	
7	IO_L08P_7	P34	